



**RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 2827**

PATENT
Attorney Docket No. 401188/FUKAMI

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

MISUMI et al.

Application No. 09/848,256

Art Unit: 2827

Filed: May 4, 2001

Examiner: L. Thai

For: **SEALED SEMICONDUCTOR
DEVICE AND LEAD FRAME USED
FOR THE SAME**

**PENDING CLAIMS AFTER AMENDMENTS
MADE IN RESPONSE TO OFFICE ACTION DATED MAY 6, 2002**

10. A sealed semiconductor device comprising:
a semiconductor chip;
a lead frame including internal leads extending across part of and spaced from a surface of said semiconductor chip; and
a die pad separate from and not continuously connected to said lead frame and on which said semiconductor chip is mounted, wherein said lead frame includes protrusions extending substantially perpendicular to and contacting said die pad.

11. A sealed semiconductor device comprising:
a semiconductor chip;
a lead frame including internal leads extending across part of and spaced from a surface of said semiconductor chip, and
a die pad separate from and not continuously connected to said lead frame and on which said semiconductor chip is mounted, said die pad including fixed protrusions extending toward and contacting some of said internal leads.

17. The sealed semiconductor device according to claim 10, wherein said protrusions are peripheral to and do not contact said semiconductor chip.

18. The lead frame according to claim 10, wherein said die pad is substantially rectangular and includes a pair of longer sides and a pair of shorter sides and said protrusions extend proximate the pair of longer sides of said die pad.

19. The lead frame according to claim 10, wherein said die pad is substantially rectangular and includes a pair of longer sides and a pair of shorter sides and said protrusions extend proximate the pair of shorter sides of said die pad.

20. The sealed semiconductor device according to claim 21, further comprising a die pad on which said semiconductor chip is mounted.

21. A sealed semiconductor device comprising:

a semiconductor chip;

a lead frame including internal leads extending across part of and spaced from a surface of said semiconductor chip; and

a tape member located between said semiconductor chip and said internal leads to hold said semiconductor chip and said internal leads at a fixed distance from each other, said tape member having a first surface to which said internal leads are entirely bonded and fixed and a second surface, not fixed to but contacting the surface of said semiconductor chip.

22. A lead frame and tape for a sealed semiconductor device having a rectangular semiconductor chip sealed within an encapsulating resin, the lead frame and tape comprising:

internal leads extending toward and electrically connected with wires to respective pads located approximately along a central axis of the semiconductor chip; and

a tape including four tape members, each tape member having a first surface to which some of said internal leads are fixed, each of said tape members being arranged at a respective corner of the semiconductor chip so that a portion of a second surface of each of said tape members contacts a surface of the semiconductor chip when the semiconductor chip is sealed within the encapsulating resin.